

# 33<sup>rd</sup> RD50 workshop – CERN, 26-28/11/2018

## Performance of thin planar n-on-p silicon pixels after HL-LHC radiation fluences



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LPNHE & UPD, Paris



# Outline

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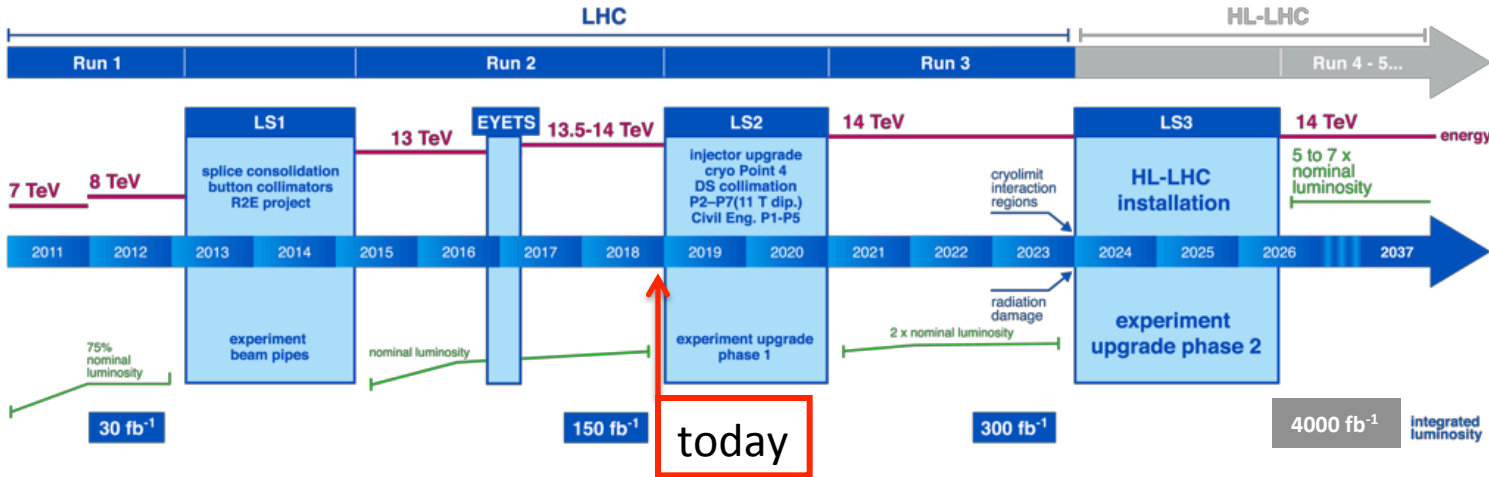
- Introduction on the LPNHE planar pixel productions
- Second production: radiation hardness of thin pixel detectors
- Third production: edge efficiency and radiation hardness of thin pixel detectors
- All productions: comparison of biasing structures
- Conclusions and outlook

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# INTRODUCTION

# High Lumi LHC (HL-LHC) challenges

## LHC / HL-LHC Plan

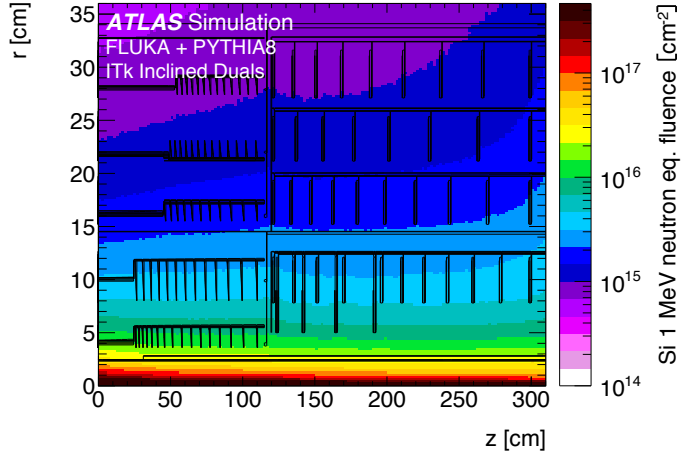


Higher luminosity to fully exploit LHC physics reach potential

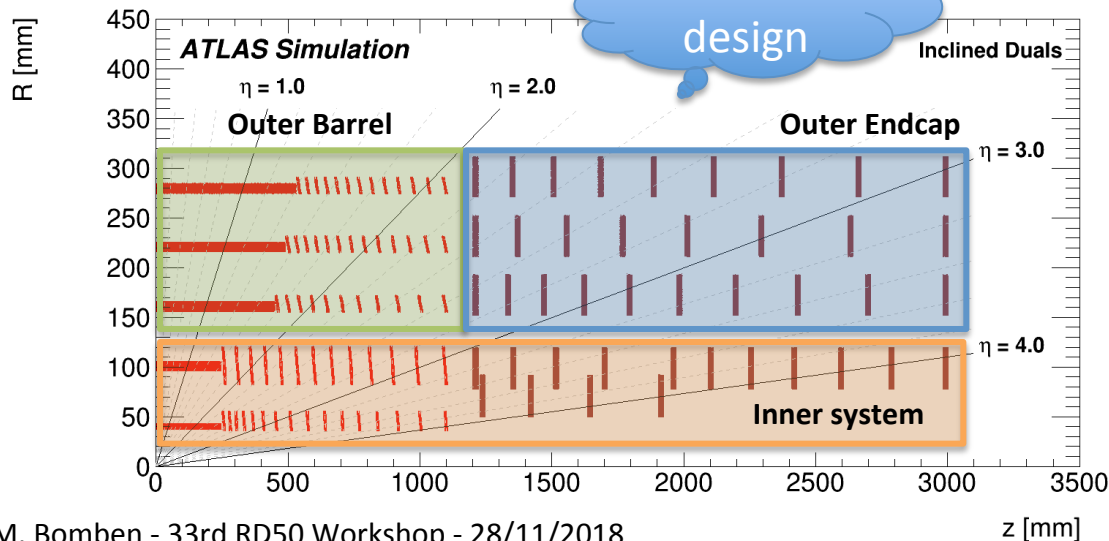
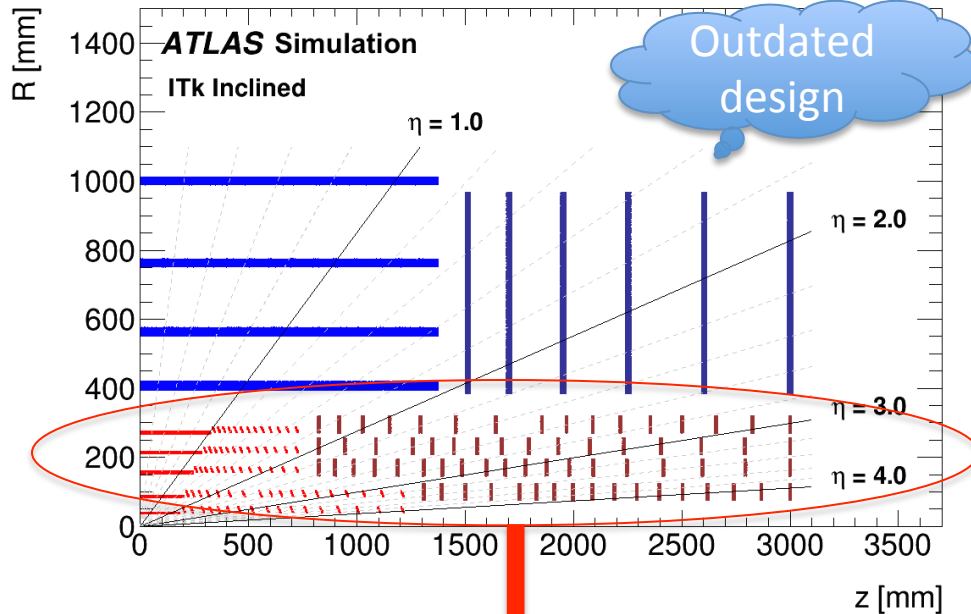
Parameter	LHC	HL-LHC
instantaneous luminosity $L$ [ $\text{cm}^{-2}\text{s}^{-1}$ ]	$1.0 \times 10^{34}$	$7.5 \times 10^{34}$
average number of pile-up events $\mu$	25	200
track rate density for the innermost pixel layer $\mathcal{N}$ [ $\text{MHz cm}^{-2}$ ]	0.25	2
fluence to the innermost pixel layer $\Phi$ [ $1 \text{ MeV } n_{\text{eq}}/\text{cm}^2$ ]	$5 \times 10^{15}$	$2 \times 10^{16}$
total ionising dose to the innermost pixel layer TID [MRad]	160	1700

Much harsher environment in terms of:

- Event rate
- Number of collisions
- **Radiation damage to tracking detectors**



# ATLAS Inner Tracker (ITk)



- Replacement of Inner Detector
- All Silicon system (pixels+strips)
- Coverage down to  $|\eta|=4$
- **Pixels detector:**  $> 10 \text{ m}^2$  of  $50 \times 50 \mu\text{m}^2$  pixels
- New inclined geometry:
  - ✓ Larger coverage
  - ✓ Less material

➤ Radiation hardness:

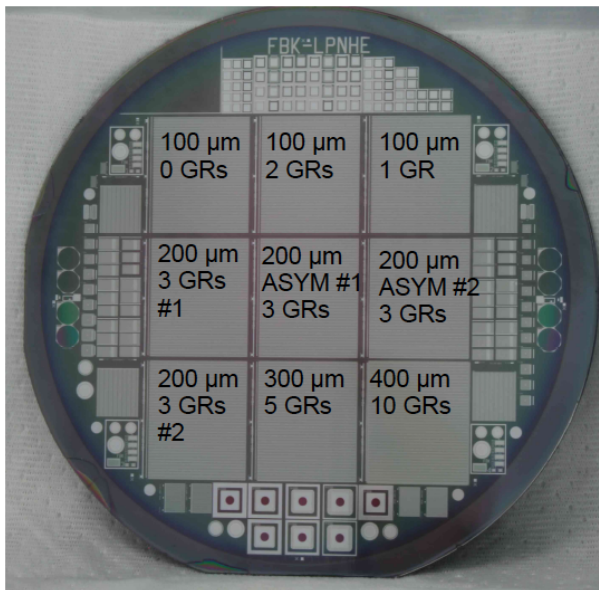
➤ 3D for innermost layers

➤ **Thin planar everywhere else**

➤ **ITk requirement: hit eff.  $> 97\%$**

# LPNHE planar pixel productions

## PAE1

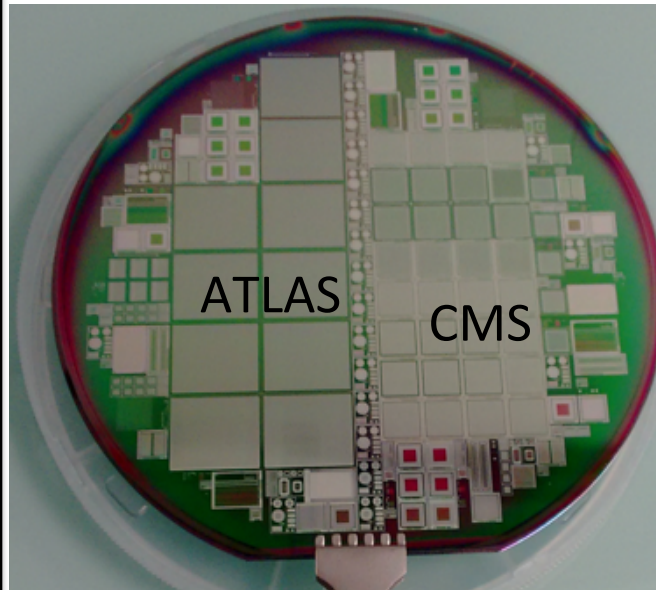


4" 200  $\mu\text{m}$  thick n-on-p  
Active Edge technology  
Pixel-to-edge down to 100  $\mu\text{m}$   
Tested extensively on beam

NIM A 712 (2013) 41–47

JINST 12 P05006 (2017)

## P2

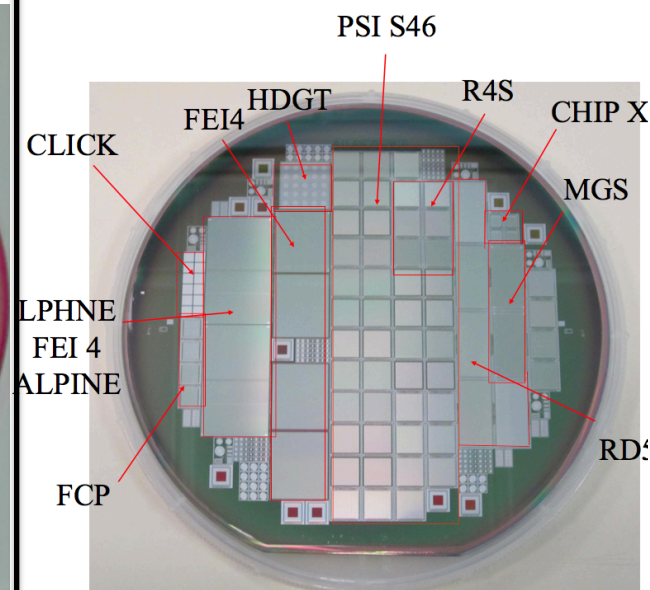


6" **130  $\mu\text{m}$  thick** n-on-p  
INFN ATLAS/CMS project  
Tested extensively on beam,  
after irradiation too

2017 JINST 12 C12038

arXiv:1810.07279

## PAE3

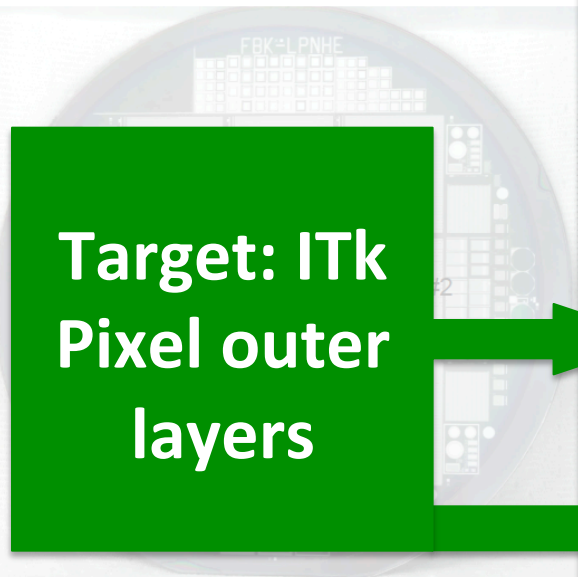


6" **130  $\mu\text{m}$  thick** n-on-p  
INFN ATLAS/CMS project  
Active Edge technology  
Pixel-to-edge down to 50  $\mu\text{m}$   
RD53 compatible sensors  
Measured on beam,  
after irradiation too

NIM A 2018 – in press

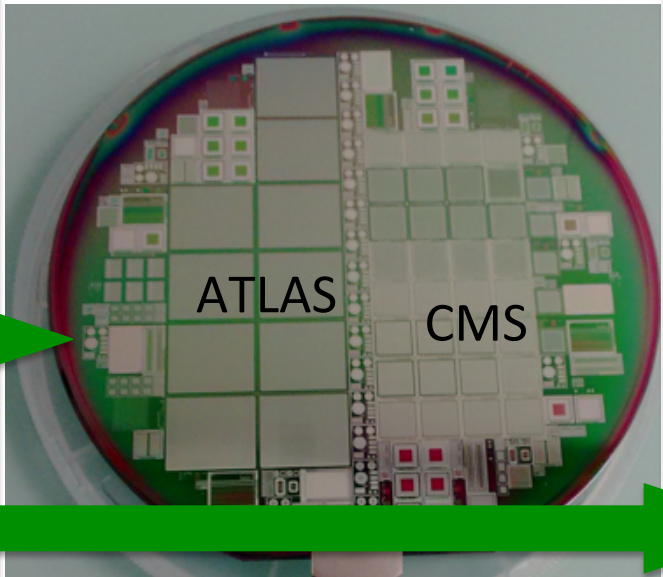
# LPNHE planar pixel productions

PAE1

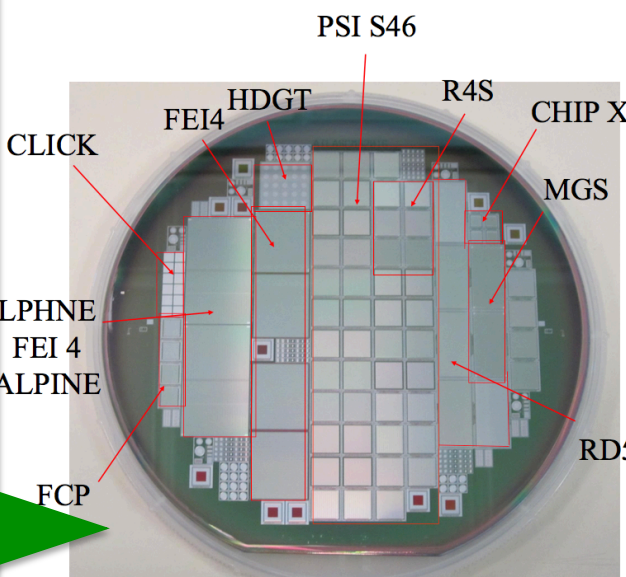


**Target: ITk  
Pixel outer  
layers**

P2



PAE3



4" 200  $\mu\text{m}$  thick n-on-p  
Active Edge technology  
Pixel-to-edge down to 100  $\mu\text{m}$   
Tested extensively on beam

6" **130  $\mu\text{m}$  thick** n-on-p  
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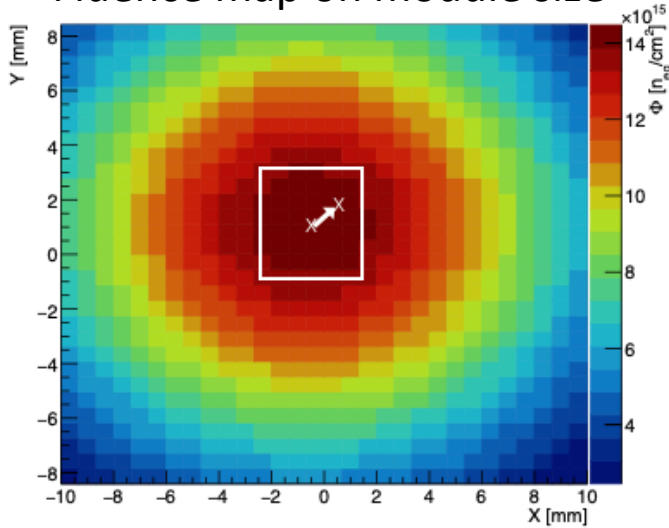
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# **SECOND PRODUCTION: RADIATION HARDNESS OF THIN PIXEL DETECTORS**



# Irradiated pixel detectors

Fluence map on module size

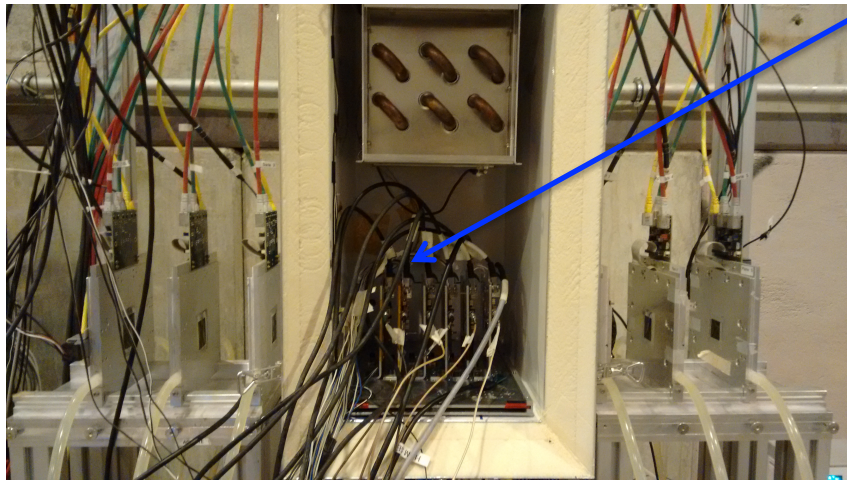


130  $\mu$ m thick FE-I4 detector irradiated up to  $1.4e16$   $n_{eq}/cm^2$  at CERN IRRAD (24 GeV/c protons)

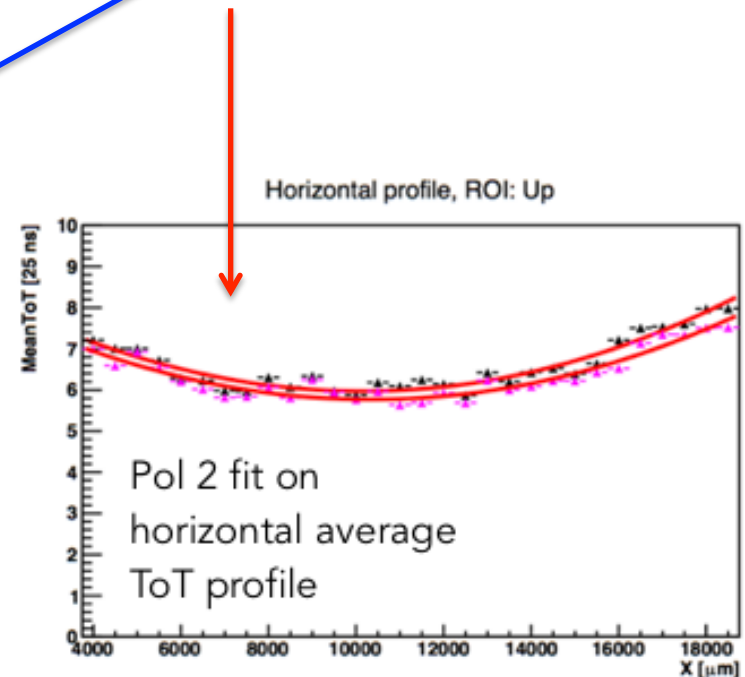
Gaussian beam profile (20 x 20 mm<sup>2</sup> FWHM)

Position unc.  $\sim 2 \times 2$  mm<sup>2</sup> (for ref. white box in the map)

Peak position re-calculated on data (white arrow in the map)

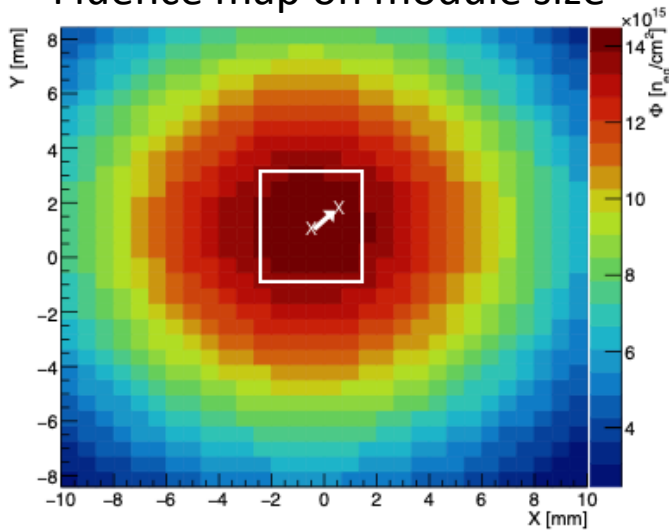


Module measured w/ 120 GeV  $\pi$



# Irradiated pixel detectors

Fluence map on module size

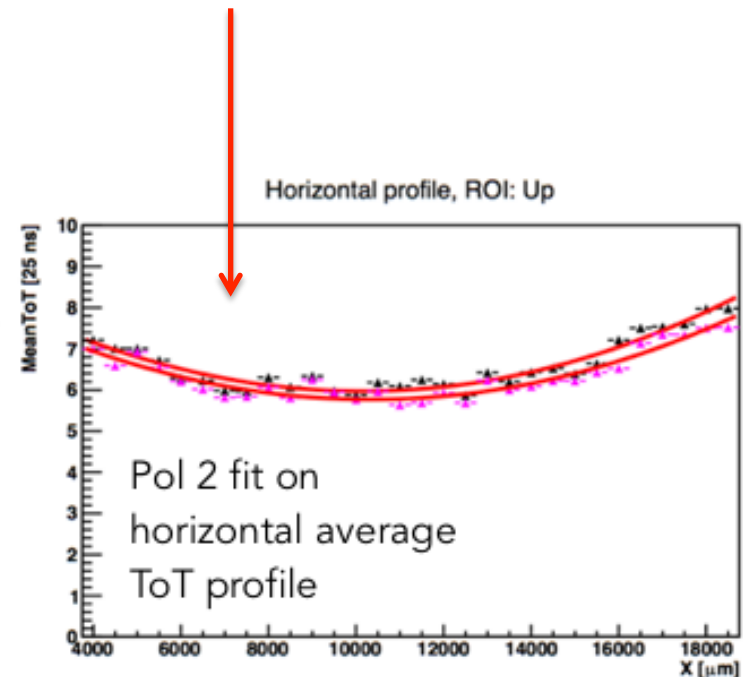
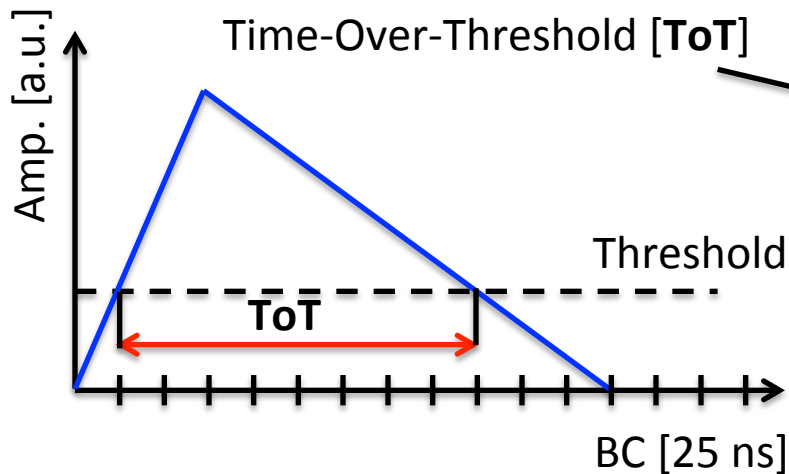


130  $\mu\text{m}$  thick FE-I4 detector irradiated up to  $1.4e16$   $n_{eq}/\text{cm}^2$  at CERN IRRAD (24 GeV/c protons)

Gaussian beam profile (20 x 20 mm<sup>2</sup> FWHM)

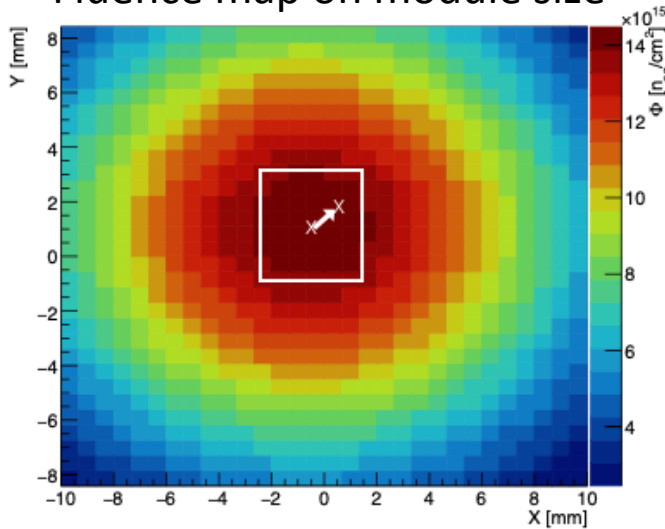
Position unc.  $\sim 2 \times 2$  mm<sup>2</sup> (for ref. white box in the map)

Peak position re-calculated on data (white arrow in the map)



# Irradiated pixel detectors

Fluence map on module size



130  $\mu\text{m}$  thick FE-I4 detector irradiated up to  $1.4 \times 10^{16} n_{eq}/\text{cm}^2$  at CERN IRRAD (24 GeV/c protons)

Gaussian beam profile (20 x 20 mm<sup>2</sup> FWHM)

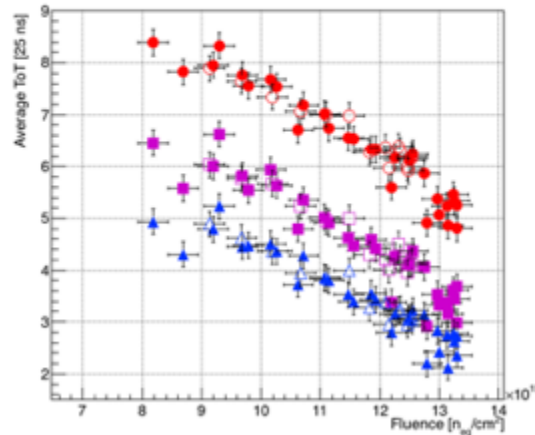
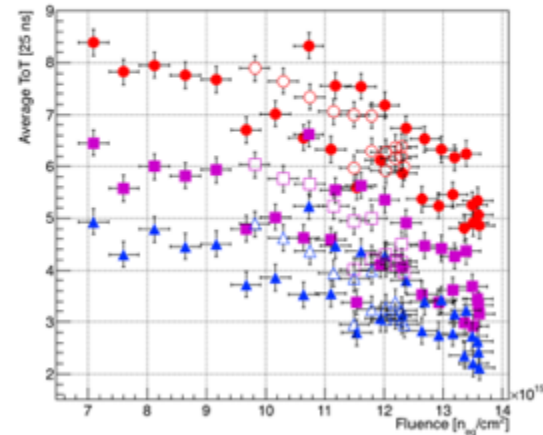
Position unc.  $\sim 2 \times 2 \text{ mm}^2$  (for ref. white box in the map)

Peak position re-calculated on data (white arrow in the map)



No Fluence peak constraint

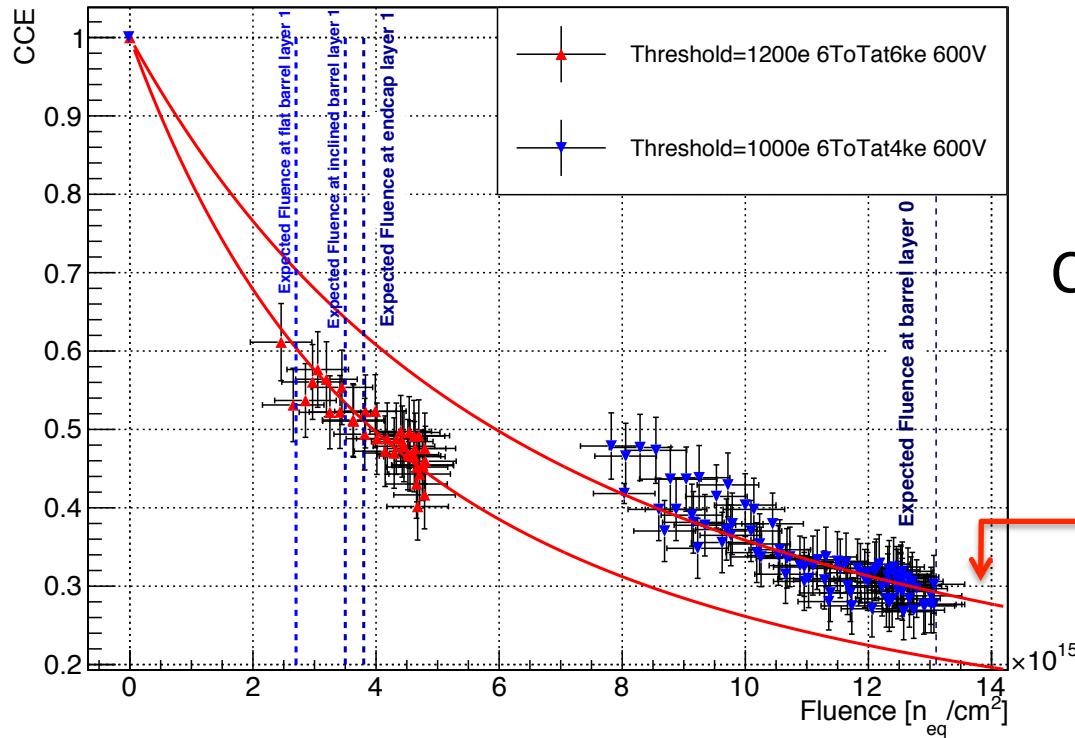
With Fluence peak constraint



- Data-driven approach
- Adjustment within uncertainties
- Much less charge dispersion

# Thin pixel performance

## Charge Collection Efficiency (CCE)



Hor. uncertainty bar → fluence

Ver. uncertainty bar → ToT dispersion

CCE down to 50% for innermost planar pixel layer

Fit with Hecht formula\*  
 $\beta = (3.6 \times 10^{-16} \pm 0.1) \text{ cm}^2/\text{ns}$   
 for large fluences

To be interpreted as a lower limit

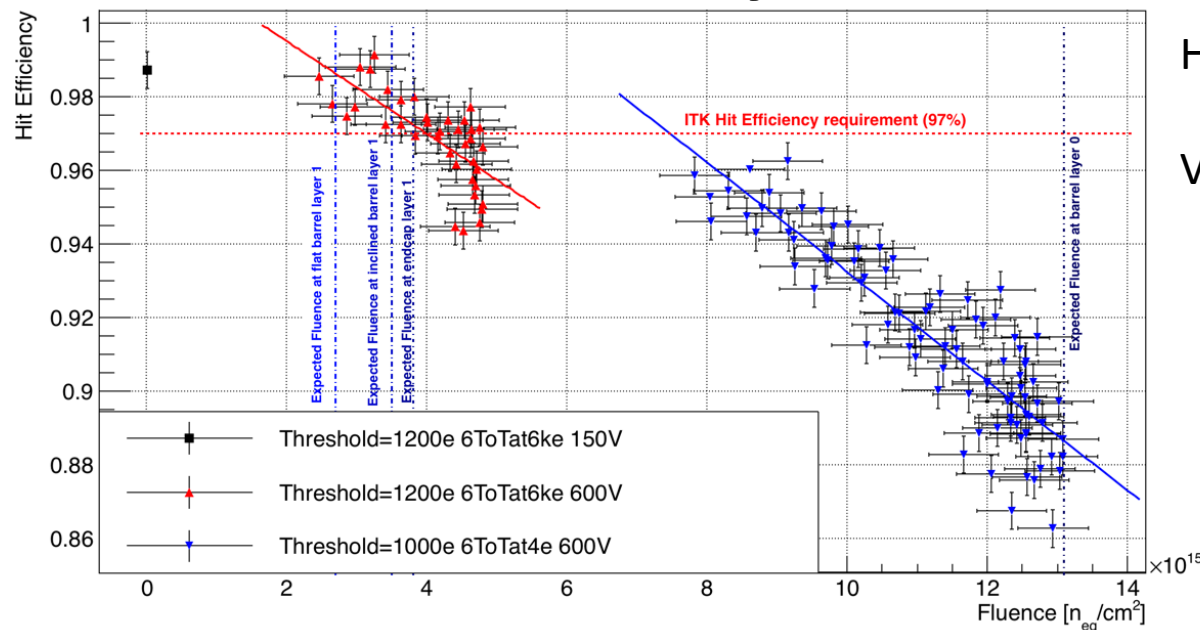
Calibration	Fluences ( $\Phi = 1 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$ )			
	2.7	3.5	3.8	13.1
Thr.=1200e, 6ToT at 6000e, CCE =	61%	53%	51%	21%
Thr.=1000e, 6ToT at 4000e, CCE =	71%	64%	62%	29%

[arXiv:1810.07279](https://arxiv.org/abs/1810.07279)

\*Zeit. Physik. (1932) 77:235

# Thin pixel performance

## Hit efficiency



Hor. uncertainty bar → fluence

Ver. uncertainty bar → statistical

**Hit eff. > 97% for fluence  
≤ 7.5e15 n<sub>eq</sub>/cm<sup>2</sup>**



arXiv:1810.07279

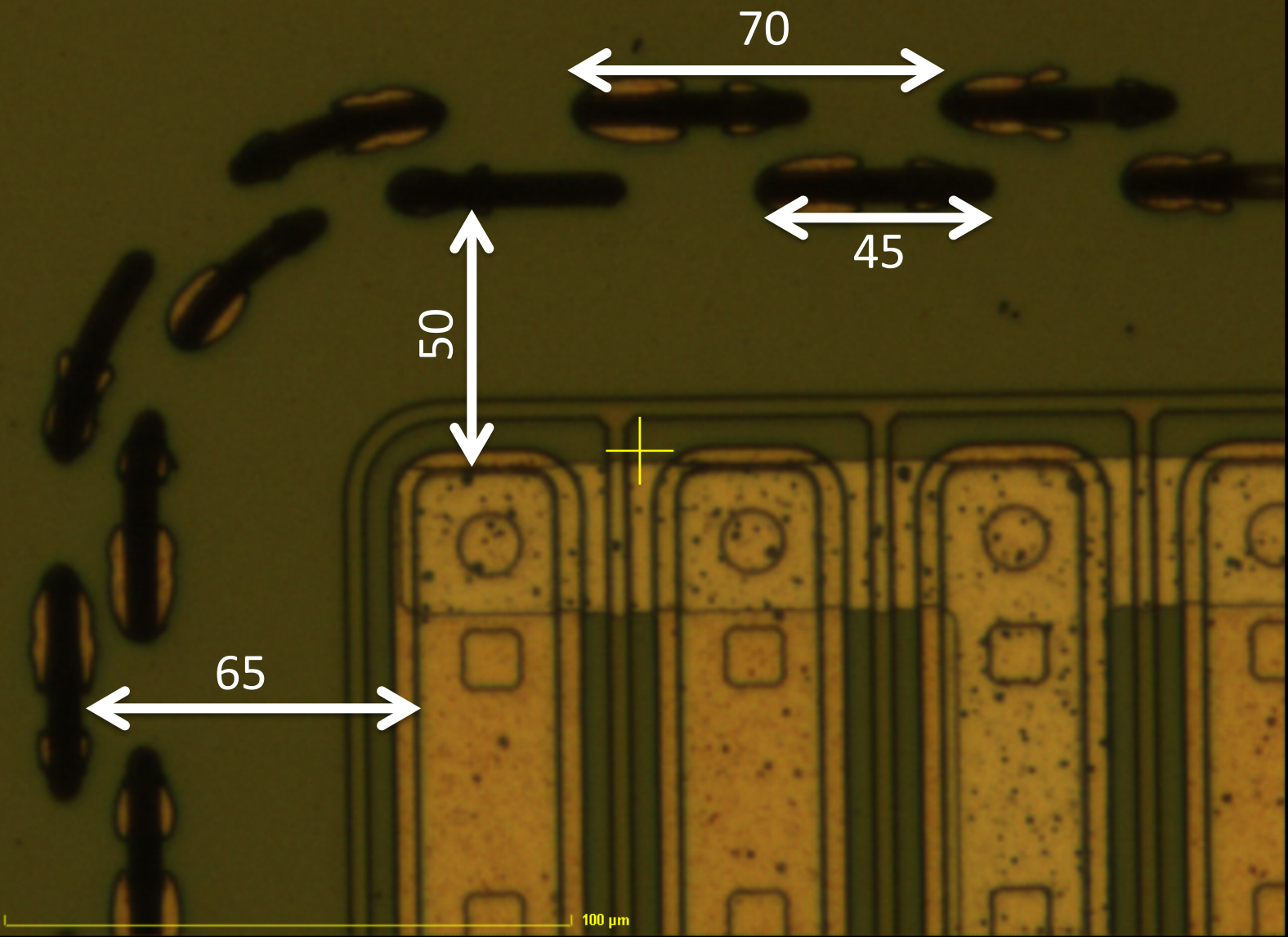
Fluence ( $\Phi = 1 \times 10^{15} n_{eq}/cm^2$ )	2.7	3.5	3.8	7.45	13.1
Threshold (electrons)	1200	1200	1200	1000	1000
ToT tuning (ToT corresponding to ke-)	6 at 6	6 at 6	6 at 6	6 at 4	6 at 4
Extrapolated Hit Efficiency (%)	98.6	97.6	97.2	97.0	88.6

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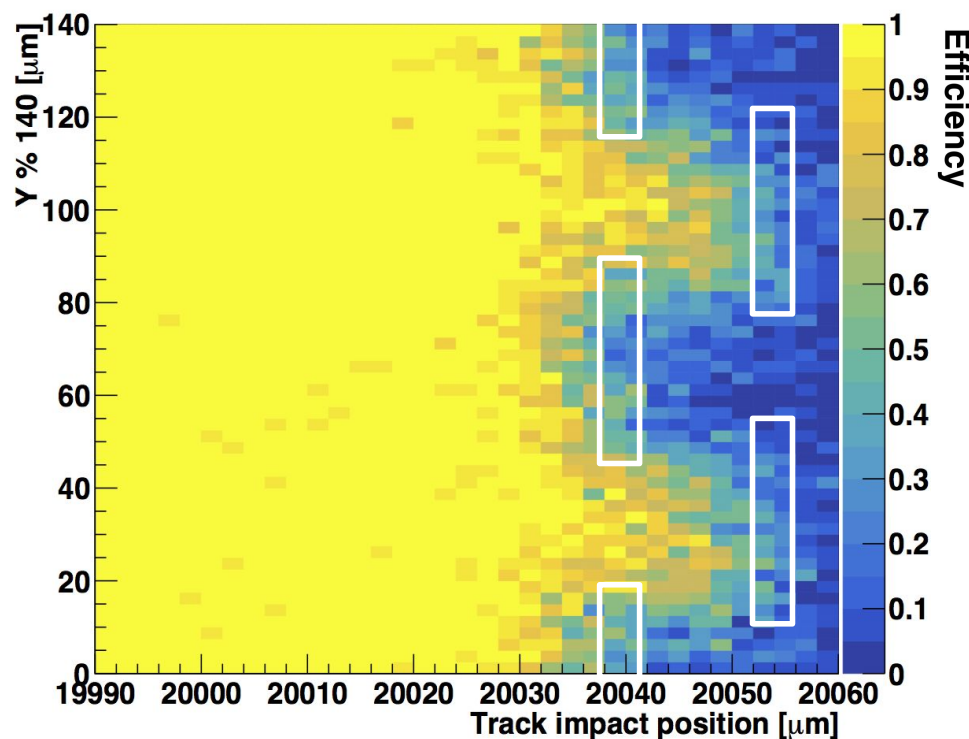
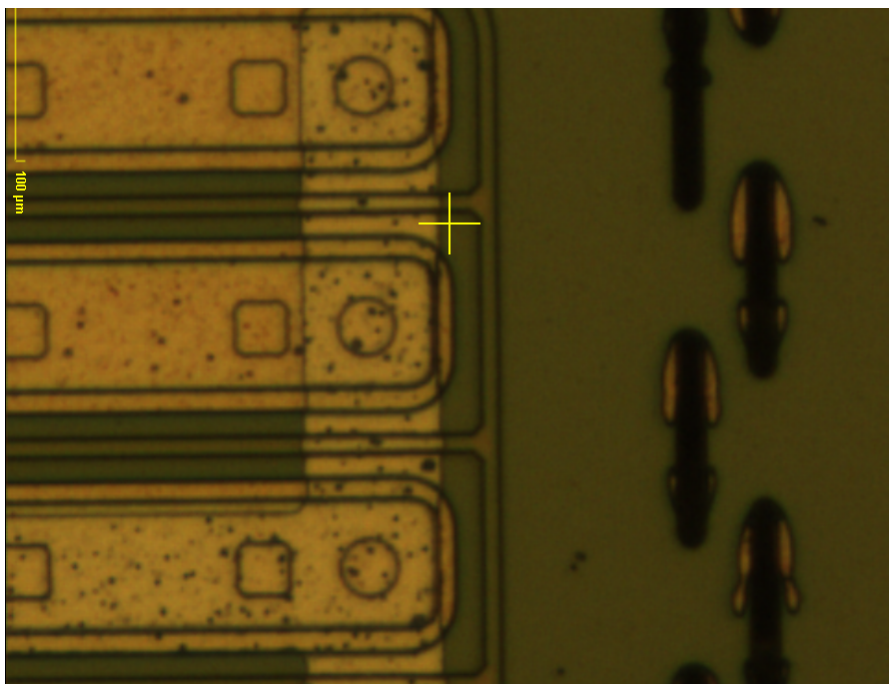
**THIRD PRODUCTION:  
EDGE EFFICIENCY AND RADIATION  
HARDNESS OF THIN PIXEL  
DETECTORS**

# PAE3 sensor with staggered trenches

[Scope]



# Active-edge performance before irradiation



130 μm thick sensor with **staggered trenches**, no GRs, ~50 μm last pixel to last edge 2 fences of discontinued edges (such sensors do not require a support wafer)

The efficiency follows the edge pattern

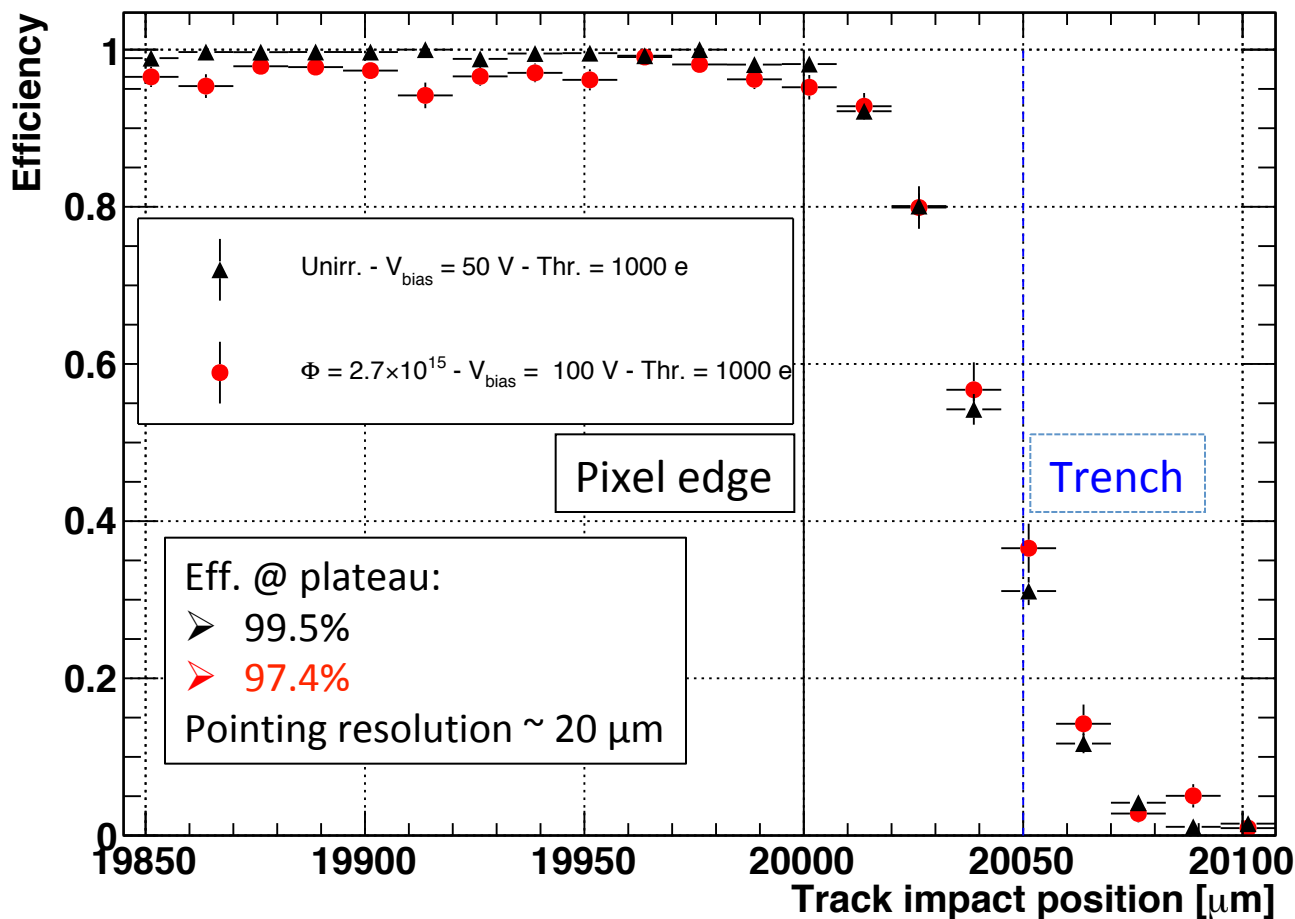
The efficiency is higher than 50% up to 44 μm from the last pixel



# Active-edge performance after irradiation

NIM A 2018 – in press

Uniform irradiation at KIT (23 MeV p)  
 $\Phi = 2.7 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$



Edge efficiency after **irradiation** + in soft BD conditions:

Comparable to **unirradiated** performance

Efficiency higher than 80% up to 25 μm from last pixel

Module measured w/ 4 GeV electrons

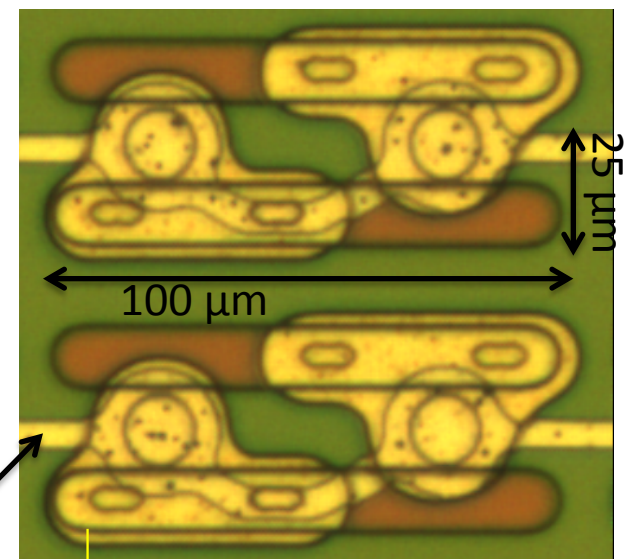
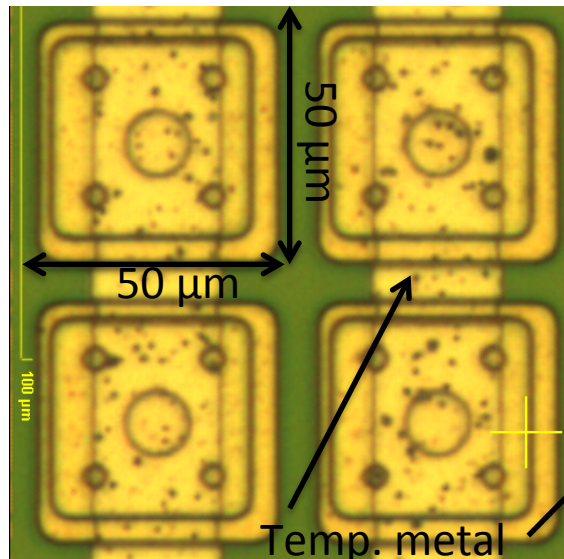
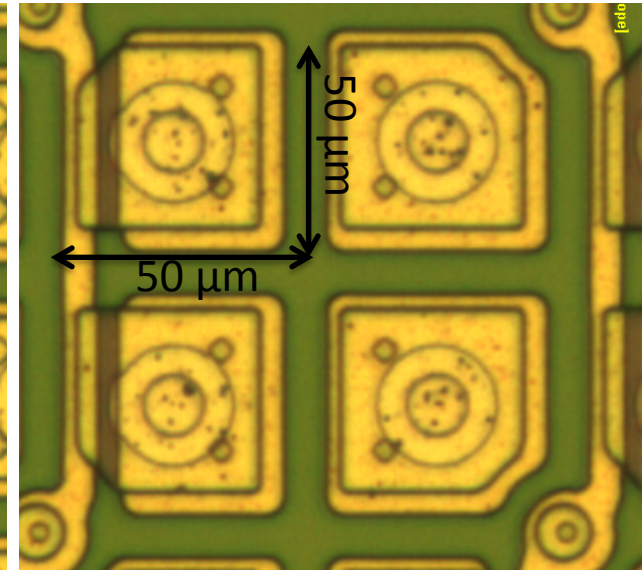
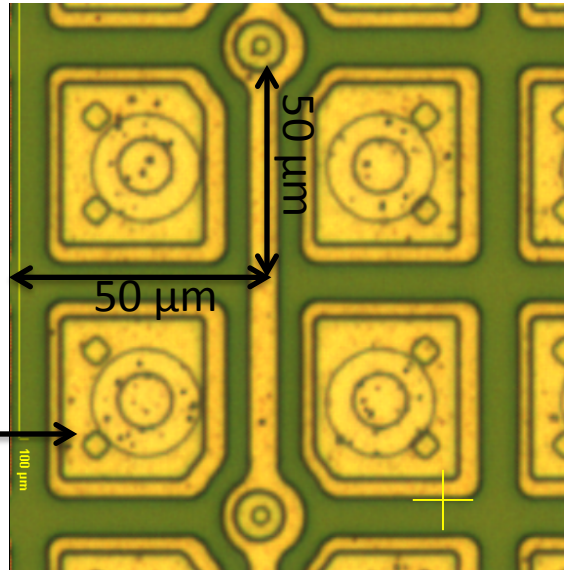
# RD53A compatible sensors

Different solutions implemented on the wafer;

2 designs with bias dot

Temporary metal for  $50 \times 50 \mu\text{m}^2$  and  $25 \times 100 \mu\text{m}^2$

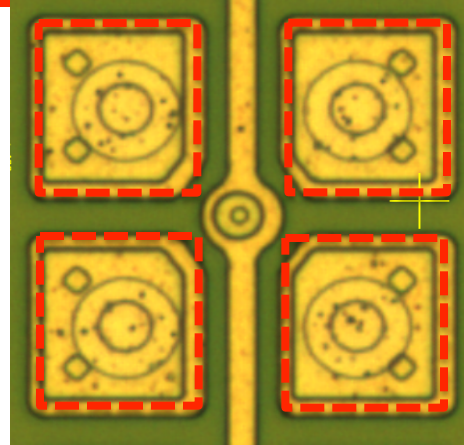
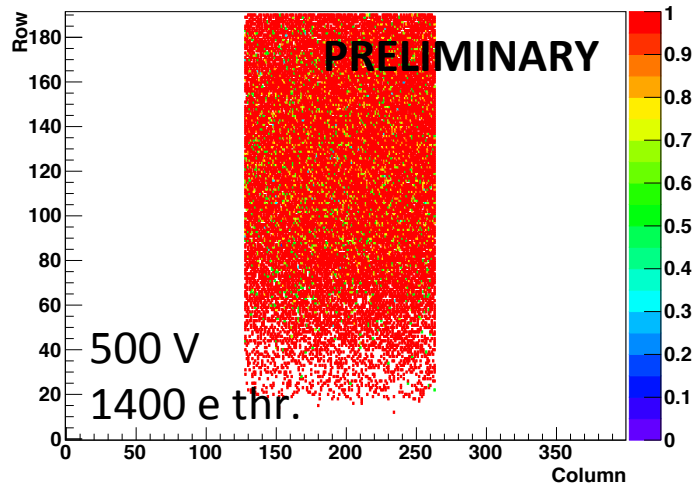
In the following preliminary results after irradiation of this design ( $50 \times 50 \mu\text{m}^2$  & bias dot)



Results in preparation also for the  $25 \times 100$  design

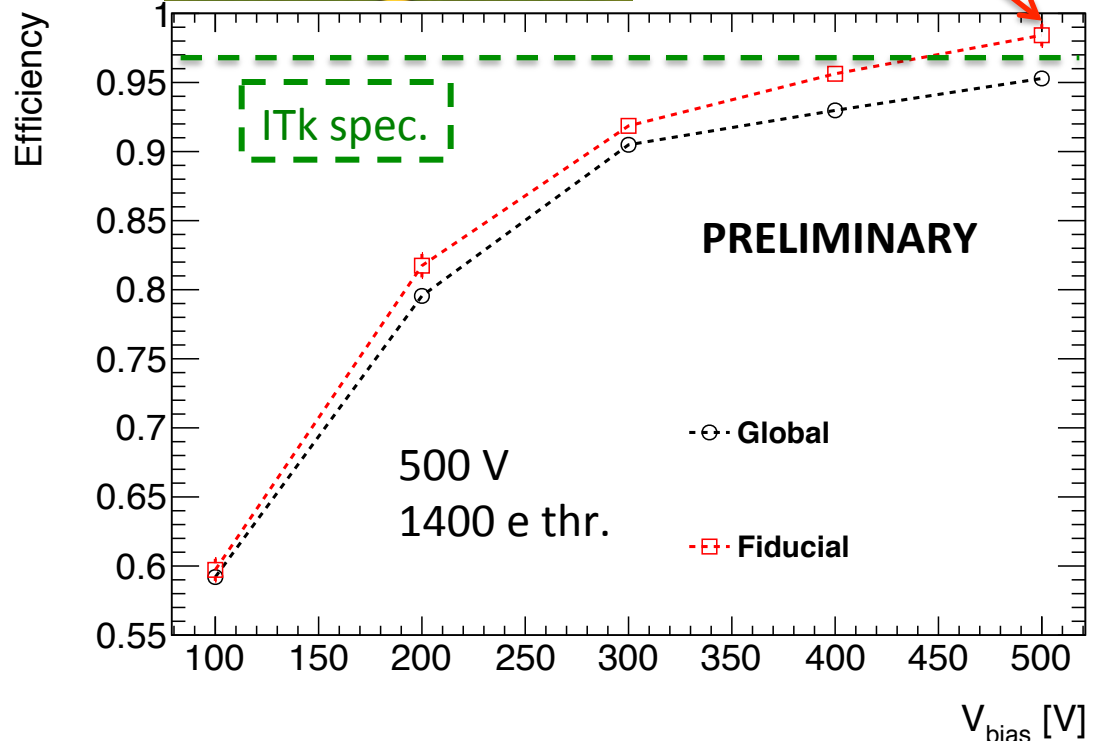
# Performance of irradiated RD53A

Irr. at CERN IRRAD @  $\langle\Phi\rangle = 5 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$   
Fluence map being reconstructed



Inner (fiducial) region

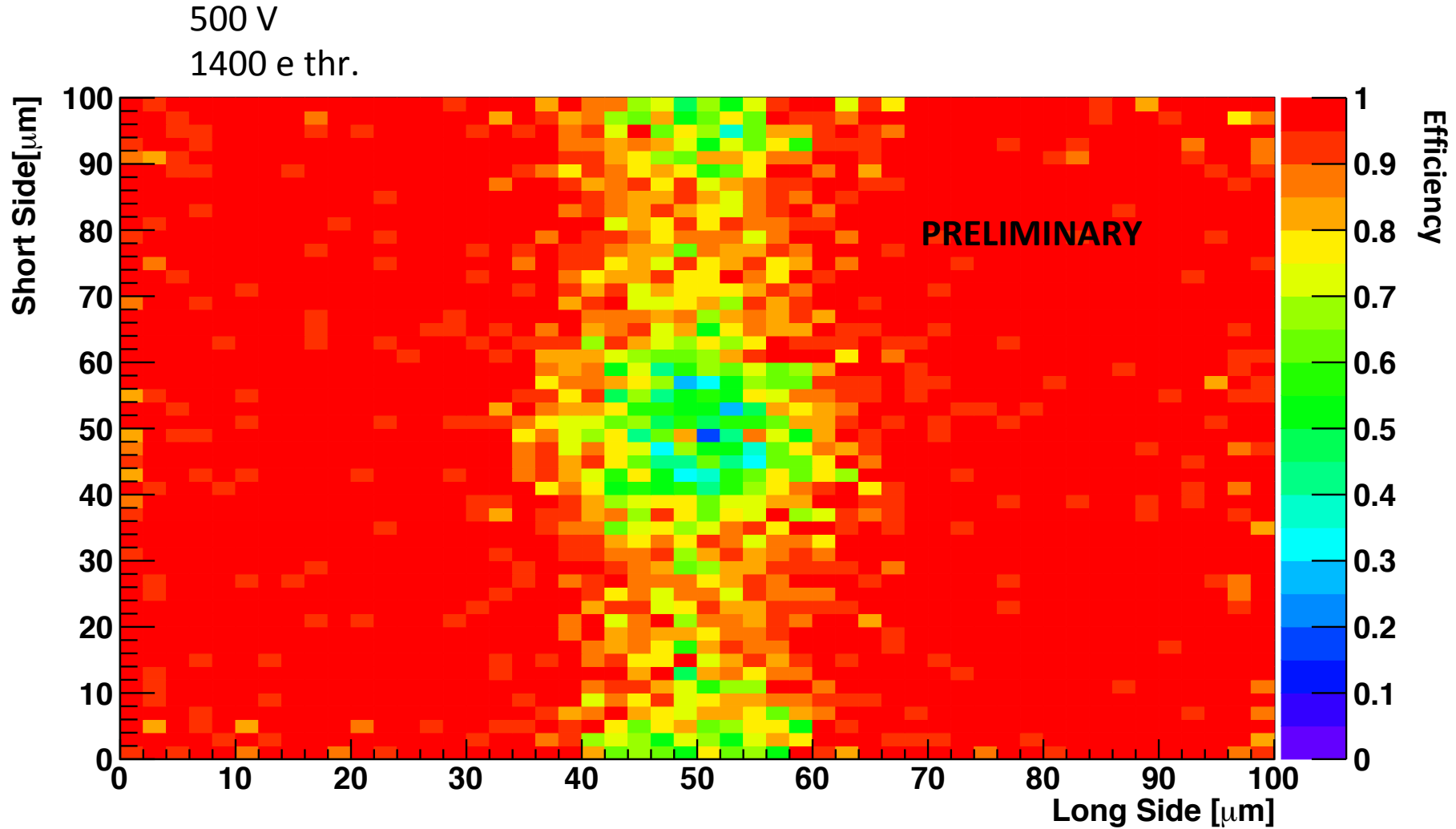
98.4% @ 500 V



Significant efficiency loss when whole matrix is considered

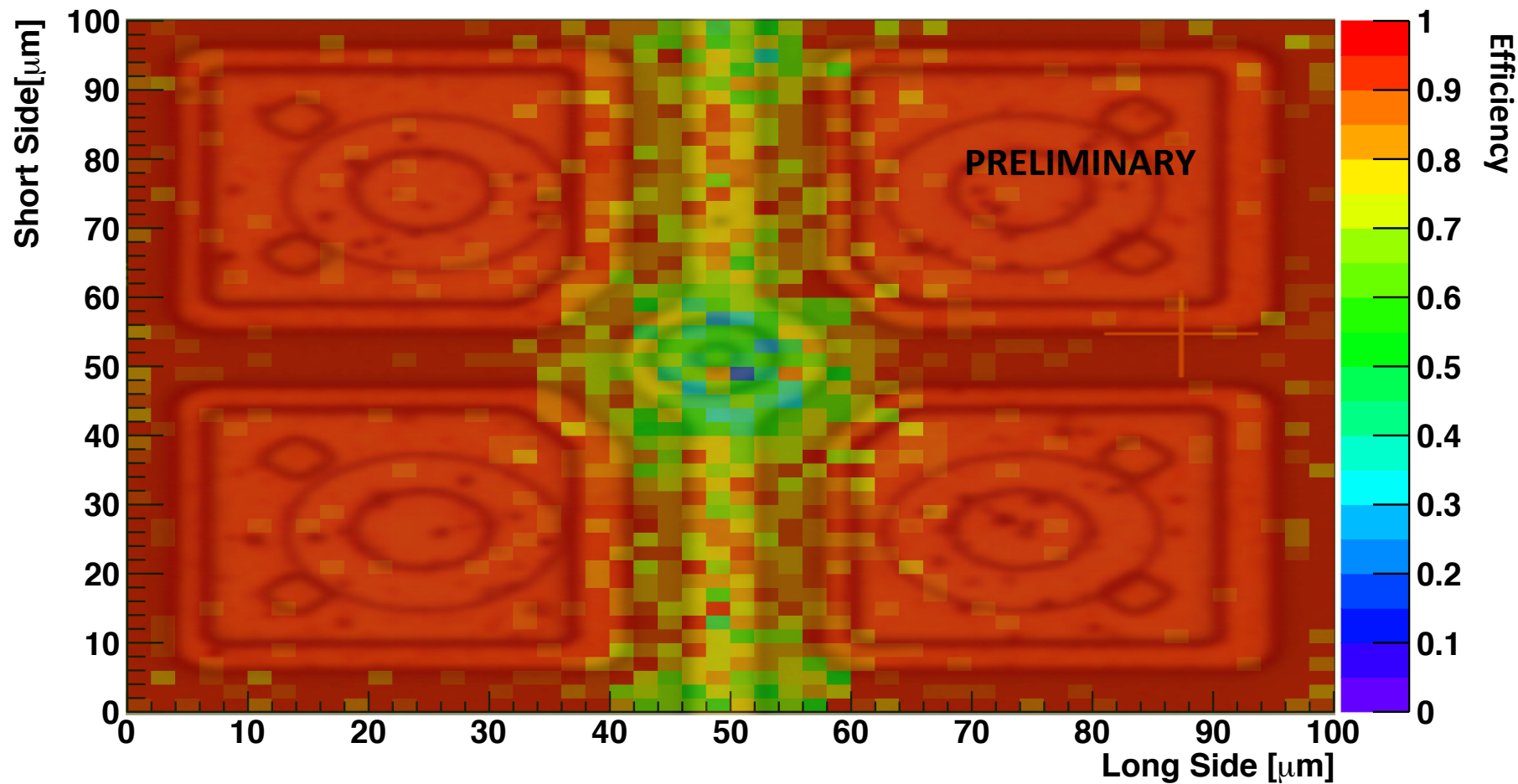
Restricting analysis to the inner part of the cell brings back > 97% hit efficiency

# Hit efficiency map



# Hit efficiency map

500 V  
1400 e thr.

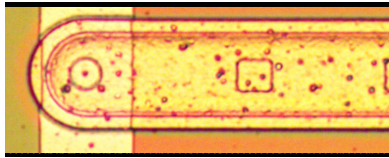


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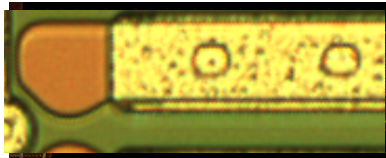
# **ALL PRODUCTIONS: COMPARISON OF BIASING STRUCTURES**

# Biasing structures

LPNHE 7 - PAE1  
Temporary Metal



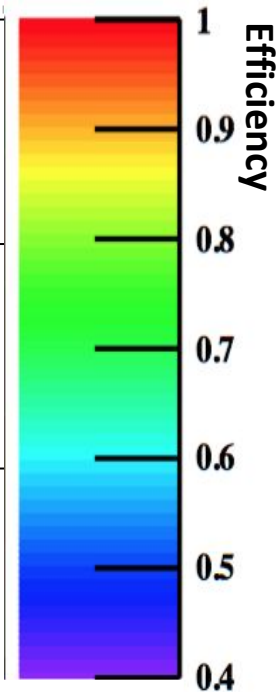
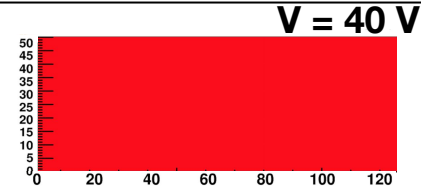
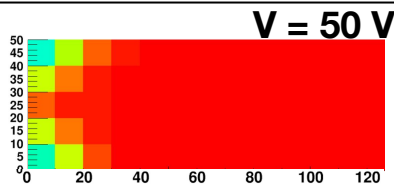
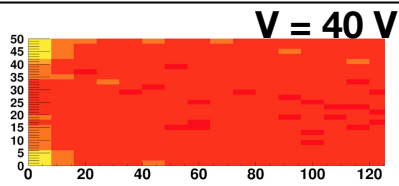
W80 - P2  
Bias Dot



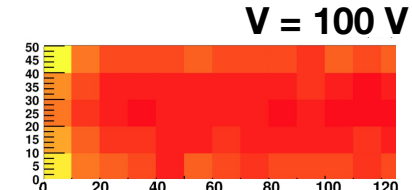
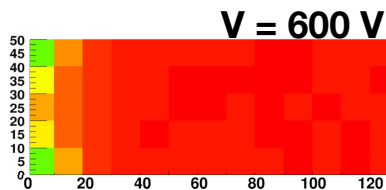
M1.4 - PAE3  
Temporary Metal



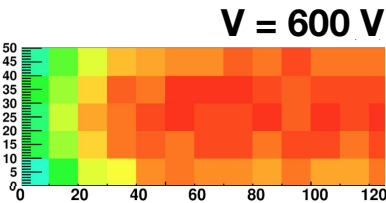
Un-irradiated



Fluence  
 $3 \times 10^{15} n_{eq}/cm^2$



Fluence  
 $1 \times 10^{16} n_{eq}/cm^2$



Temporary metal considered for ITk. We were the first to propose it for planar

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# CONCLUSIONS & OUTLOOK



# Conclusions & outlook

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- Unprecedented HL-LHC radiation fluences demand for radiation hard pixel detectors
- Thin n-on-p planar pixels sensors produced at FBK by LPNHE proved to meet the stringent ATLAS Inner Tracker specifications after HL-LHC like fluences
- New small pitch pixels show once more the interest of using temporary metal as biasing solution, assuring large and uniform hit-efficiency, after irradiation too
- Next steps: test more prototypes and improve pixel cell design

# Acknowledgments

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The second and third production were supported by the Italian National Institute for Nuclear Physics (INFN), Projects ATLAS, CMS, RD-FASE2 (CSN1):

Principal investigators: Marco Meschini, Gian Franco Dalla Betta, Maurizio Boscardin, Giovanni Darbo, Gabriele Giacomini, Sabina Ronchin, Alberto Messineo

Irradiations and testbeam supported by AIDA-2020 Project EU-INFRA  
Proposal no. 654168



Many thanks to all ITk pixel testbeam community

**THANK YOU  
FOR YOUR ATTENTION!**

# Backup

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# Hecht formula

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$$\text{CCE} = \frac{Q}{Q_0} = \left[ \frac{d_e + d_h}{w} \right] - \left( \frac{d_e}{w} \right)^2 \left( 1 - e^{-\frac{w}{d_e}} \right) - \left( \frac{d_h}{w} \right)^2 \left( 1 - e^{-\frac{w}{d_h}} \right)$$

$$d_e = v_e^{(sat)} \tau_e = \frac{v_e^{(sat)}}{\beta_e \phi}$$

Same for holes

(Brutal) approximations:

- saturated velocities
- 1D Ramo potential
- (From TCAD) same saturation velocity for electrons and holes

Full derivation also here:

M. Bomben - 2018

<https://tel.archives-ouvertes.fr/tel-01824535>